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Serial No. 09/253,611

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Paul A. Farrar	Examiner:	Ron Pompey
Serial No.:	09/253,611	Group Art Unit:	2812
Filed:	February 19, 1999	Docket:	303.572US1
Title:	SELECTIVE DEPOSITION OF SOLDER BALL CONTACTS		

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Commissioner for Patents
Washington, D.C. 20231

Applicant has reviewed the Office Action mailed on August 27, 2002. Please consider the following remarks.

REMARKS

No claims are amended, canceled, or added; as a result, claims 1, 3-12, 64, 65, 68, and 71 are now pending in this application.

Information Disclosure Statement

Applicant respectfully requests that a copy of the 1449 Form, listing all references that were submitted with the Information Disclosure Statement filed on January 17, 2002, marked as being considered and initialed by the Examiner, be returned with the next official communication.

§112 Rejection of the Claims

Claims 1, 9, and 11 (their dependent claims also) were rejected under 35 USC § 112, first paragraph, as containing subject matter which was not described in the specification in such a way as to reasonably convey to one skilled in the relevant art that the inventor(s), at the time the application was filed, had possession of the claimed invention. The amendment filed 1-30-02 was incorrectly entered, because the limitations of "selectively depositing solder only on the exposed portion of the metal contact without depositing solder on the insulating layer" has no support from the originally presented claims or drawings. Therefore, the amendment filed 5-31-02 pertaining to these claims is also rejected based on the same reason.

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